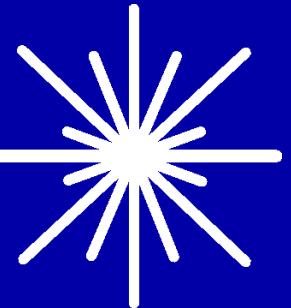


# OC Tutorial – Semiconductor Basics

May 15, 2015

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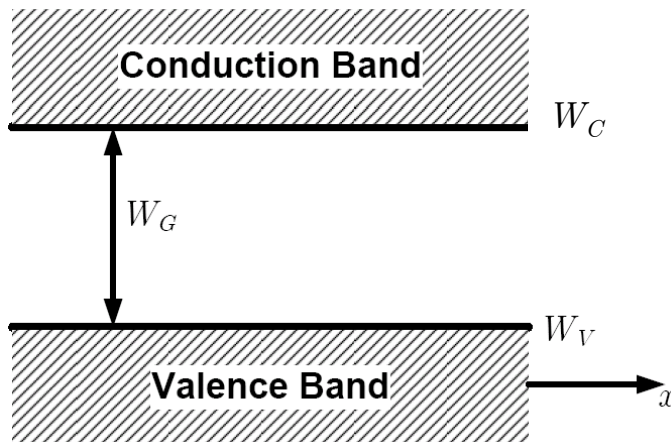
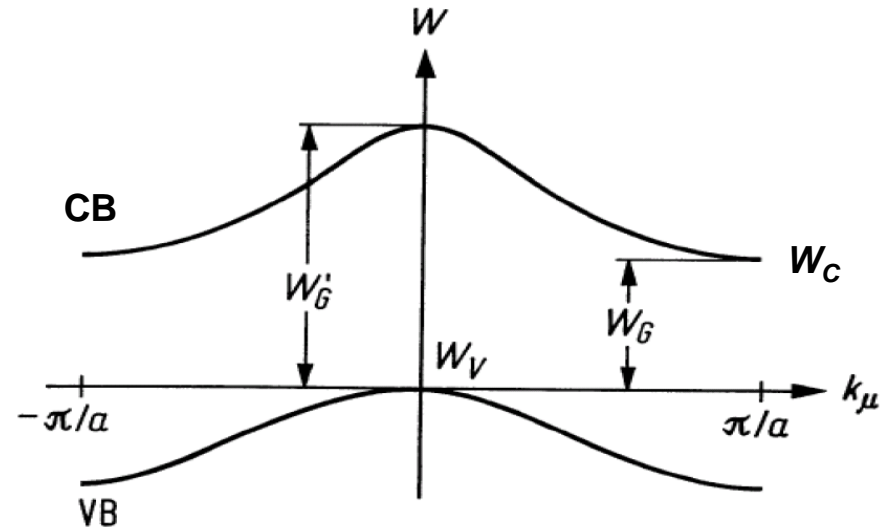
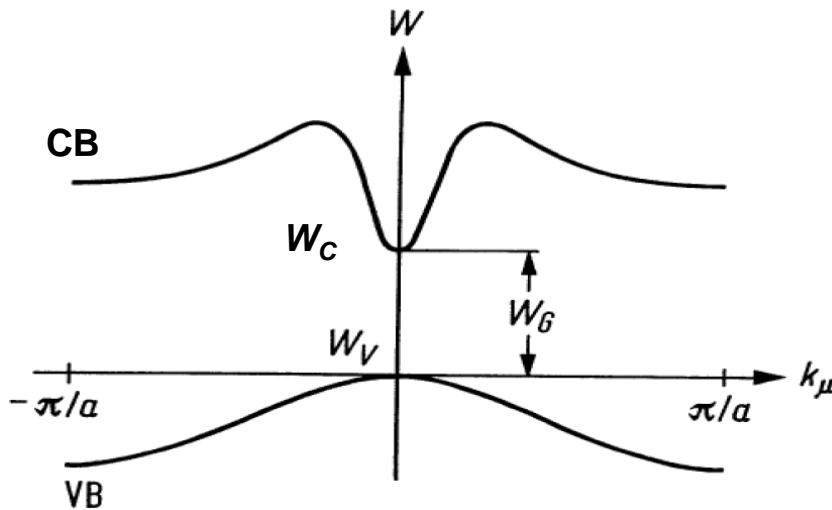
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# Direct and Indirect Semiconductors

Direct semiconductor (e.g. GaAs, InP) Indirect semiconductor (e.g. Si, Ge)



## *Direct semiconductor*

Maximum of valence band and minimum of conduction band at same  $k_\mu$ .

## *Indirect semiconductor*

Maximum of valence band and minimum of conduction band at different  $k_\mu$ .

# Intrinsic and Extrinsic Semiconductor

**Intrinsic semiconductor:** Pure semiconductor with negligible amount of impurities. Electron and hole carrier concentrations in thermal equilibrium are determined by material properties and temperature:

$$n_T = p = n_i$$

**Extrinsic semiconductor:** Doping changes carrier concentrations in thermal equilibrium. **Donors** “donate” negatively charged electrons to the conduction band (n-type). **Acceptors** “accept” additional electrons, and positively charged “holes” are created in the valence band (p-type).

**n-type:**

majorities:  $n_T \cong n_D$

minorities:  $p_{n0} = n_i^2 / n_D$

Typical doping concentrations:  $10^{15} \text{ cm}^{-3}$  to  $10^{18} \text{ cm}^{-3}$

Intrinsic *and* extrinsic semiconductor in thermal equilibrium (**mass-action law**):  $n_T p = n_i^2$

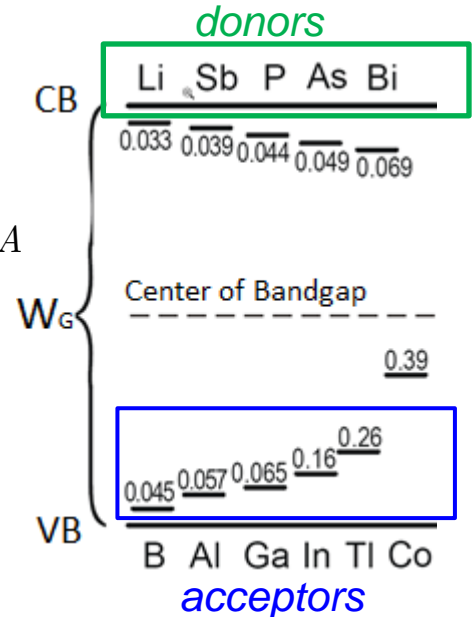
**Neutrality** condition:

$$n_T + n_A = p + n_D$$

**p-type:**

majorities:  $p \cong n_A$

minorities:  $n_{p0} = n_i^2 / n_A$



# Carrier Concentration at Thermal Equilibrium

*Density of states* in the conduction band ( $\rho_C$ , number of electron states per energy interval), and in the valence band ( $\rho_V$ , number of hole states per energy interval):

$$\rho_C(W) = \frac{1}{2\pi^2} \left( \frac{2|m_n|}{\hbar^2} \right) \sqrt{W - W_C} \quad \rho_V(W) = \frac{1}{2\pi^2} \left( \frac{2|m_p|}{\hbar^2} \right) \sqrt{W_V - W}$$

*Carrier concentration* in conduction band ( $n_T$ ) and valence band ( $p$ ):

$$n_T = \int_{W_C}^{\infty} \rho_C(W) f(W) dW \quad p = \int_{-\infty}^{W_V} \rho_V(W) [1 - f(W)] dW$$

$f(W)$  is the *Fermi-Dirac distribution function*.  $f(W)$  is the probability that a state at energy  $W$  is occupied by an electron.

$1 - f(W)$  is the probability that a state at energy  $W$  is not occupied by an electron, i. e., that it is occupied by a hole.



# Fermi-Dirac Distribution Function

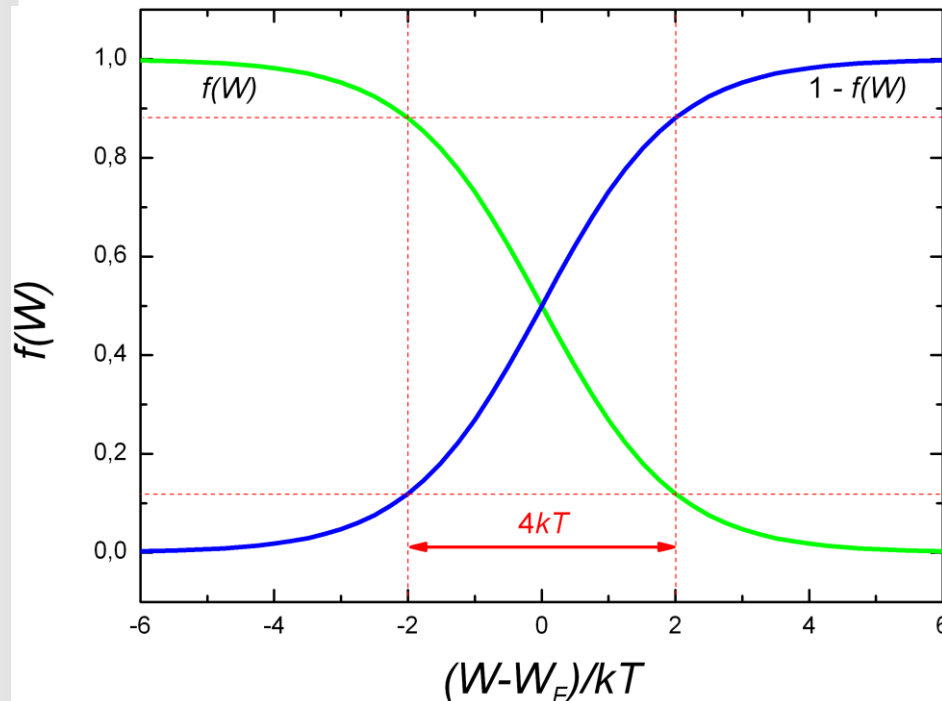
$$f(W) = \frac{1}{1 + \exp\left(\frac{W - W_F}{kT}\right)}$$

$$1 - f(W) = \frac{1}{1 + \exp\left(\frac{W_F - W}{kT}\right)}$$

$k$  Boltzmann's constant

$kT$  Thermal energy  
 $kT = 25\text{meV}$  at  $T = 293\text{K}$

$W_F$  Fermi energy



- At Fermi energy,  $f(W_F) = 0.5$
- Position of Fermi level:
  - Intrinsic: Between  $W_V$  and  $W_C$
  - n-type:  $W_F$  moves towards  $W_C$
  - p-type:  $W_F$  moves towards  $W_V$
- Transition region:  
 $(0.88 > f > 0.12) \rightarrow \text{width } 4kT$   
 $\Delta f = 4kT/h = 24.2 \text{ THz}$



# Boltzmann Approximation

If the Fermi level is far away ( $> 3kT$ ) from the band edges  $W_C$  and  $W_V$  (as is the case for doping concentration of  $n_D \ll N_C$  and  $n_A \ll N_V$ ), then **Boltzmann's approximation** holds:

$$f(x) = \frac{1}{1 + \exp x} \stackrel{x \gg 1}{\approx} \frac{1}{\exp x} \quad \Longrightarrow \quad \begin{aligned} f_V(W) &= \exp\left(-\frac{W_F - W}{kT}\right) \\ f_L(W) &= \exp\left(-\frac{W - W_F}{kT}\right) \end{aligned}$$

Solving the integrals for the carrier concentrations with Boltzmann's approximation gives:

$$\begin{aligned} n_T &= N_C \exp\left(-\frac{W_C - W_F}{kT}\right) \quad \text{with} \quad N_C = 2 \left( \frac{2\pi m_n kT}{h^2} \right)^{3/2} \\ p &= N_V \exp\left(-\frac{W_F - W_V}{kT}\right) \quad \text{with} \quad N_V = 2 \left( \frac{2\pi m_p kT}{h^2} \right)^{3/2} \end{aligned} \quad N_{C,V} \approx 10^{19} \text{ cm}^{-3}$$

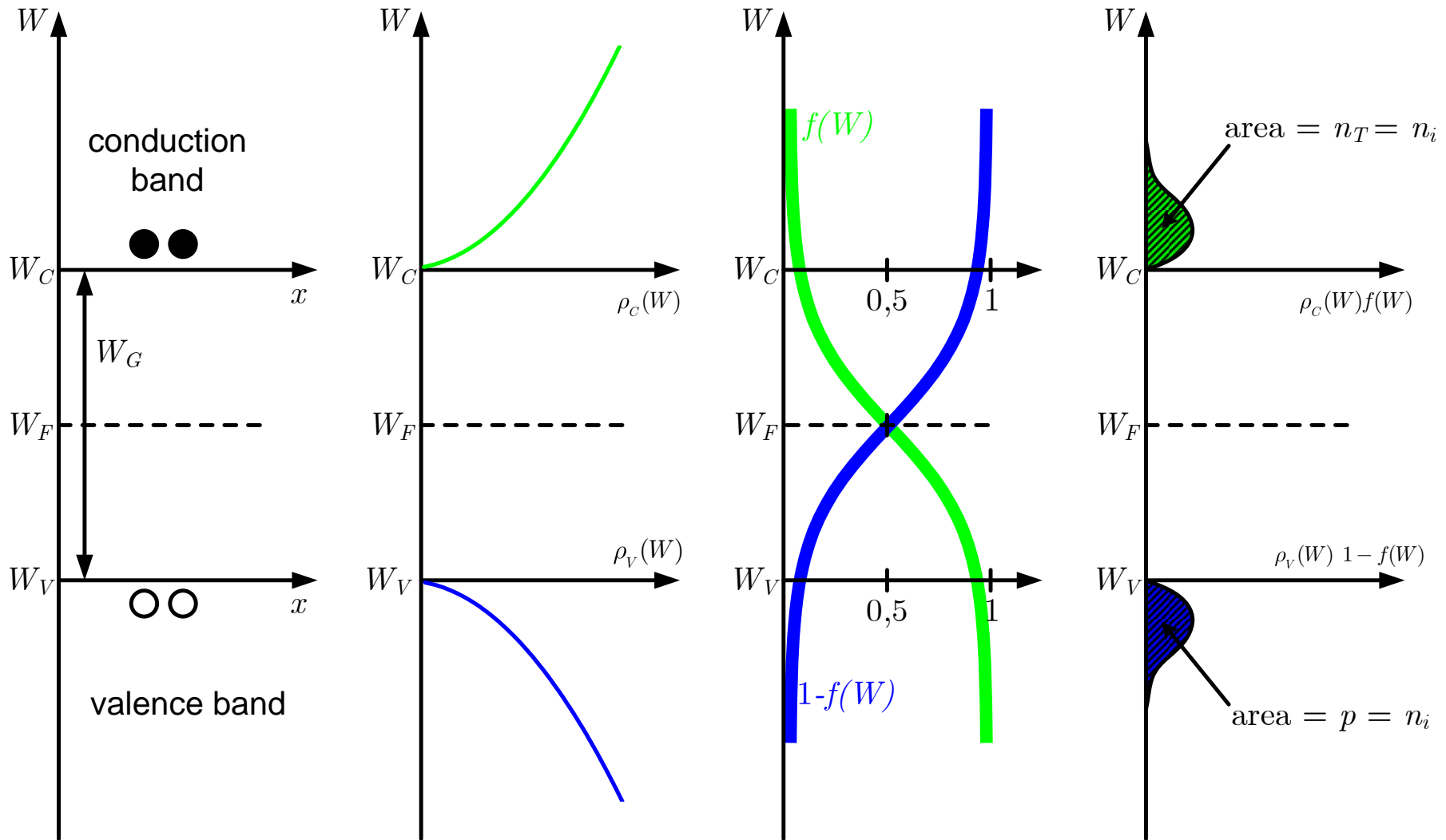
$N_C$  and  $N_V$  are called effective density of states. Within  $kT$  from the band-edge, there are  $0.75 N_{C,V}$  states. For intrinsic semiconductors follows:

$$n_i = \sqrt{n_T p} = \sqrt{N_C N_V} \exp\left(-\frac{W_G}{2kT}\right) \quad \text{and} \quad W_F = \frac{W_C + W_V}{2} + \frac{kT}{2} \ln \frac{N_V}{N_C}$$



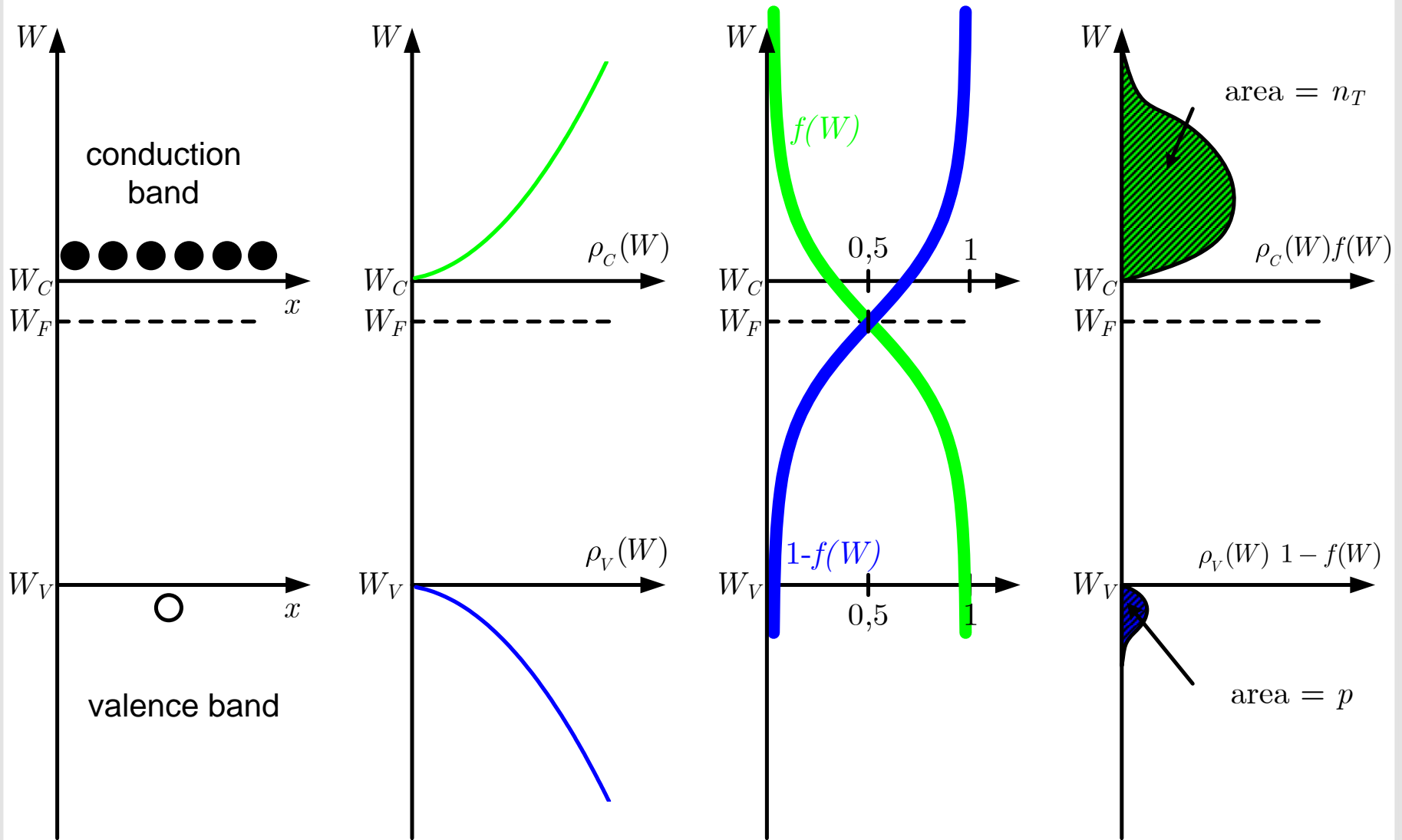
# Visual Summary of Carrier Concentrations (1)

Intrinsic semiconductor in thermal equilibrium.



# Visual Summary of Carrier Concentrations (2)

Extrinsic semiconductor (n-type) in thermal equilibrium.





# Currents in Semiconductors

**Drift current** due to an electric field  $E$ :

$$\vec{J}_F = \vec{J}_{n,F} + \vec{J}_{p,F} = en_T \mu_n + ep \mu_p \vec{E} = \sigma \vec{E}$$

$\mu_{n,p}$  carrier mobility  
 $e$  elementary charge  
 $\sigma$  conductivity

**Diffusion current** due to a gradient of carrier concentration:

$$\vec{J}_D = \vec{J}_{n,D} + \vec{J}_{p,D} = eD_n \text{grad } n_T - eD_p \text{grad } p$$

**Diffusion coefficients**  $D_n$  and  $D_p$  for electrons and holes:

$$D_n = \mu_n U_T = \mu_n \frac{kT}{e} \quad \text{and} \quad D_p = \mu_p U_T = \mu_p \frac{kT}{e}$$

$U_T = kT/e$  is called temperature voltage ( = 25 mV @  $T = 293$  K)

**Diffusion lengths**  $L_n$  and  $L_p$  for electrons and holes:

$$L_n = \sqrt{D_n \tau_n} \quad \text{and} \quad L_p = \sqrt{D_p \tau_p}$$

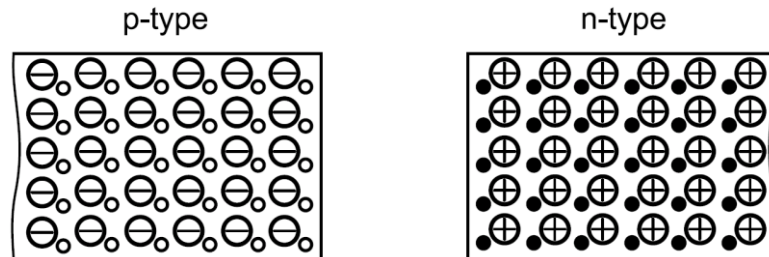
$\tau_n, \tau_p$  are the minority carrier lifetimes of electrons and holes.



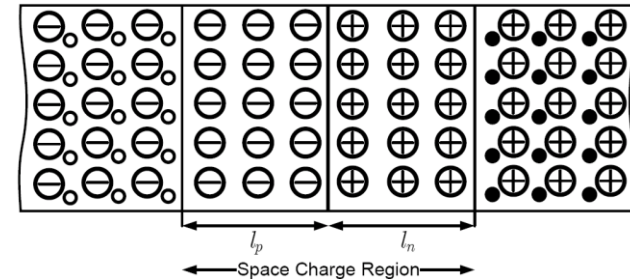
# pn-junction in Thermal Equilibrium

Bringing together a p-type and n-type semiconductor.

Before contact:



After contact:



Electrons diffuse into the p-type semiconductor, and holes into the n-type semiconductor. The positively and negatively charged donor and acceptor ions in the **space charge region (SCR)** build up an electric field that counteracts diffusion.

In thermal equilibrium, there are zero net electron and hole currents, i.e. diffusion and drift currents compensate each other:

$$\vec{J}_p = \vec{J}_{p,F} + \vec{J}_{p,D} = 0$$

$$\vec{J}_n = \vec{J}_{n,F} + \vec{J}_{n,D} = 0$$

The **built-in potential**  $U_D$  of the pn-junction is given by:

$$U_D = U_T \ln \frac{n_D n_A}{n_i^2} = \frac{kT}{e} \ln \frac{n_D n_A}{n_i^2}$$

# Current-Voltage Characteristics of pn-Diode

Applying an external voltage to the pn-junction → no equilibrium

Under *reverse bias* condition ( $U < 0$ , “+” at n-type, “-” at p-type), charge carriers are removed to increase the SCR width:  $n_T p < n_i^2$

Under *forward bias* condition ( $U > 0$ , “+” at p-type, “-” at n-type), charge carriers are injected to reduce the SCR width:  $n_T p > n_i^2$

Concentration of minority charge carriers at the edges of the SCR increase/decrease exponentially with the applied voltage  $U$ .

For example, the hole concentration change in the n-type region is:

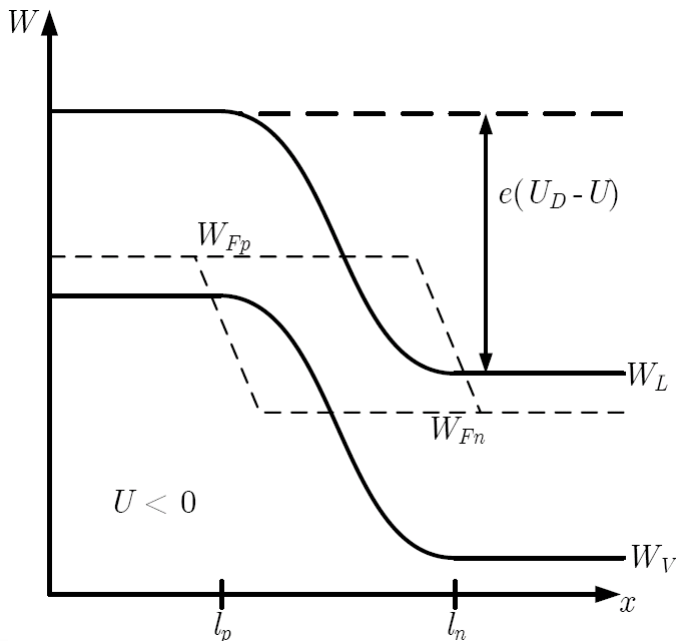
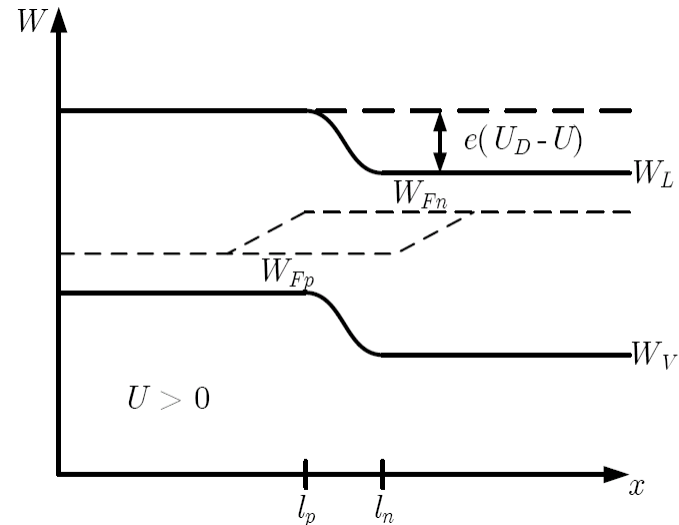
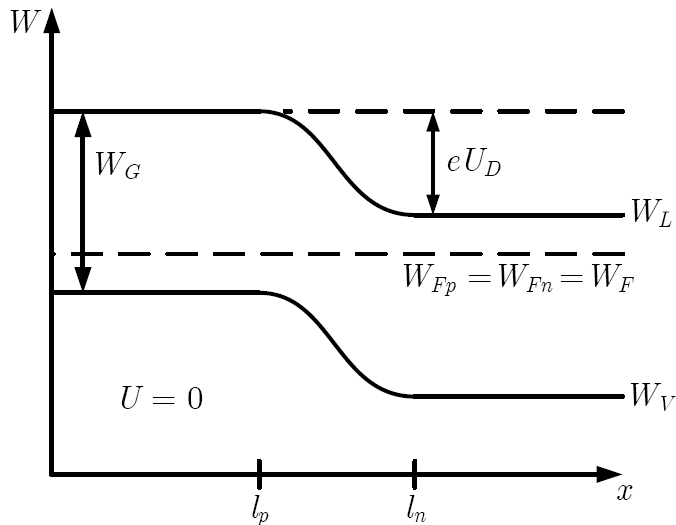
$$\Delta p_n(l_n) = p_{n0} \left( \exp\left(\frac{U}{U_T}\right) - 1 \right) \quad \Delta p_n(x) = p_{n0}(l_n) \exp\left(-\frac{x - l_n}{L_p}\right)$$

Assuming only diffusion currents outside the SCR, the current-voltage characteristics of the pn-diode follows as:

$$I = F \underbrace{\left( \frac{eD_n}{L_n} n_{p0} + \frac{eD_p}{L_p} p_{n0} \right)}_{\text{Saturation current } I_s} \left( \exp\left(\frac{eU}{kT}\right) - 1 \right) = I_s \left( \exp\left(\frac{U}{U_T}\right) - 1 \right)$$



# Band Diagrams



In thermal equilibrium, the Fermi level is flat, i.e. no net current flows.

In non-equilibrium, the Fermi level splits up into the quasi Fermi levels (QFL)  $W_{Fn}$  and  $W_{Fp}$ . A gradient of the QFL indicates current flow.

$U > 0$  reduces barrier for carriers

$U < 0$  increases barrier for carriers



# Depletion-Layer and Diffusion Capacitance

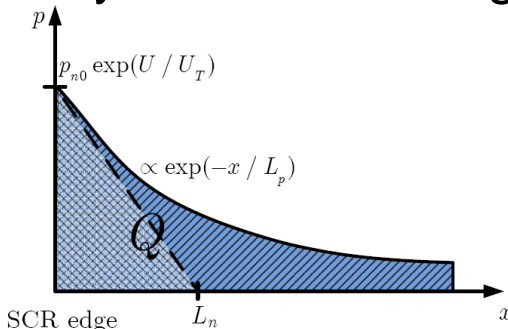
**Depletion-layer capacitance** (dominating if reverse biased): The total width of the SCR varies according to the applied voltage. Thus also the amount of charges in the SCR changes. Taking the formula for a parallel plate capacitor yields:

$$C_S = \varepsilon_0 \varepsilon_r \frac{F}{w(U)} \quad \text{with} \quad w(U) = l_n - l_p = \sqrt{\frac{2\varepsilon_0 \varepsilon_r}{e} \frac{n_D + n_A}{n_D n_A} U_D - U}$$

**Diffusion capacitance** (dominating if forward biased): When applying a small AC signal, not all the minority carriers at the edge of the SCR follow the signal instantaneously. The stored minority charge (here: holes in an n-type semiconductor) is given by:

$$Q = eF \int_0^{\infty} p_{n0} \exp\left(\frac{U}{U_T}\right) \exp\left(-\frac{x}{L_p}\right) dx = eFL_p p_{n0} \exp\left(\frac{U}{U_T}\right)$$

Only half of the charge is modulated effectively:



$$Q = I\tau \quad G_0 = \frac{\delta I}{\delta U} = \frac{I}{U_T}$$

$$C_D = \frac{1}{2} \frac{\delta Q}{\delta U} = \frac{1}{2} \frac{\delta I}{\delta U} \frac{\delta Q}{\delta I} = \frac{1}{2} G_0 \tau = \frac{1}{2} \frac{I}{U_T} \tau$$

